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IN THE U.S. PATENT AND TRADEMARK OFFICE

APPLICANTS: Kenneth A. Peterson & Robert D. Watson
SERIAL NO.: Unknown GROUP NO.
FILED:
FOR: Bi-Level Microelectronic Device Package with an Integral Window
Assistant Commissioner for Patents
Washington, D.C. 20231
EXAMINER:

J1002 U.S. PTO
10/082961
02/25/02

February 25, 2002

INFORMATION DISCLOSURE STATEMENT

The following sections are being submitted for this Information Disclosure Statement:

1. Preliminary Statements

Applicants submit herewith patents, publications or other information of which they are aware, which they believe may be material to the examination of this application and in respect of which there may be a duty to disclose.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made (37 CFR 1.97(g)), an admission that the information cited is, or is considered to be, material to patentability or that no other material information exists.

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2. Form PTO - 1449 (Modified).

3. The person making this statement is the attorney or agent who signs below on the basis of the information supplied by the inventor(s) and the information in the attorney's or agent's file.

Dated: 2/25/02

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the U. S. Postal Service on the date shown below as Express Mail No. EL026587084US in an envelope addressed to the: Assistant Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

Dated: 2/25/02

Viola Campos
Viola Campos

Form PTO-1449 (SNL-Modified) (2-91)
 List of Patents and Publications
 for Applicant's
 Information Disclosure Statement
 (use several sheets if necessary)

Atty Docket No: SD-7122/S-98,720
 Serial Number:

APPLICANT: Kenneth A. Peterson, et al

GROUP: FILING DATE: 2/25/02

REFERENCE DESIGNATION

Ex'r Init		Document No.	Date	U.S. Patent Documents Name	Sub Class	Class	File Date
	AA	6,335,224	6/1/02	Protection of Microelectronic, ...	438/114		5/16/00
	AB	5,600,541	2/4/97	Vertical IC Chip Stack...	361/707		8/3/95
	AC	5,729,038	3/17/98	Silicon-Glass Bonded Wafers	257/460		12/15/95
	AD	5,357,056	10/18/94	Chip Carrier For Optical Device	174/524		3/23/93
	AE	5,864,381	1/26/99	Automated Pupil Remapping...	351/205		7/10/96
	AF	5,493,391	2/20/96	One Dimensional Wavefront...	356/121		7/11/94
	AG	5,352,852	10/4/94	Charge Coupled Device Package...	174/52.4		8/3/93
	AH	4,742,182	5/3/88	Flatpack for Hermetic...	174/52		11/6/86

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		Foreign Patent Documents	Sub	Translation		
	Document No.	Date	Name	Class	Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

- |BA |Kenneth A. Peterson, et al; "Pre-Release Plastic Packaging of MEMS and IMEMS Devices" Patent Application 09/572,720 filed 5/16/00.
- |BB |Kenneth A. Peterson, et al, "Microelectronic Device Package with an Integral Window"; Serial No. 09/571,335; filed 5/16/00; Notice of Allowance 2/6/01.
- |BC |M.L. Minges, et al., "Electronic Materials Handbook, Vol. 1, PACKAGING", ASM International, Materials Park, OH, Jan., 1989, pp. 461-469.

Examiner:	Date Considered:
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